



Docket No.: 50432-204

# 7/A  
2/12/03  
PATENT *Mullish*

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of

Minh Van NGO, et al.

Serial No.: 09/986,267

Filed: November 08, 2001

For: METHOD OF FORMING RELIABLE CU INTERCONNECTS

:  
:  
:  
:  
:  
:  
:

Group Art Unit: 2812

Examiner: J. Brophy

RECEIVED  
FEB - 3 2003  
TECHNOLOGY CENTER 2800

**AMENDMENT**

Commissioner for Patents  
Washington, DC 20231

Sir:

The following Amendment and Remarks are submitted in response to the Office  
Action dated November 1, 2002.

**IN THE CLAIMS:**

Please amend claim 10 as follows.

10. (Amended) The method according to claim 9, comprising:

treating the upper surface of the Cu or Cu alloy in a plasma containing  $[\text{NH}_4] \text{NH}_3$   
to remove copper oxide therefrom; and  
depositing a silicon nitride capping layer on the plasma treated surface by plasma  
enhanced chemical vapor deposition.

Please add new claim 16 as follows.